

TOSHIBA**TLRE261AP**

TOSHIBA LED LAMP InGaAlP RED LIGHT EMISSION

TLRE261AP

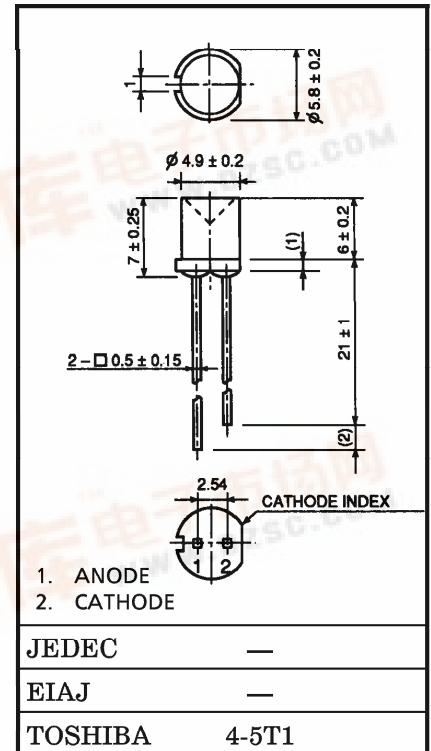
PANEL CIRCUIT INDICATOR

Unit in mm

- 5 mm DIAMETER
- InGaAlP RED LED
- All Plastic Mold Type.
- Colorless Clear Lens
- Low Drive Current, High Intensity Red Light Emission
Recommended Forward Current : $I_F = 15 \sim 20$ mA (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity
- Without Stand-offs.
- Wide Radiation Pattern.
- APPLICATIONS : Suitable for Backlighting.

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	50	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	125	mW
Operating Temperature Range	T_{opr}	$-30 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-40 \sim 120$	$^\circ\text{C}$



Weight : 0.26 g

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ELECTRICAL AND OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Forward Voltage		V_F	$I_F = 20 \text{ mA}$	—	1.85	2.4	V
Reverse Current		I_R	$V_R = 4 \text{ V}$	—	—	50	μA
Luminous Intensity	TLRE261AP	I_V	$I_F = 20 \text{ mA}$ (Note)	8.5	15	—	mcd
	TLRE261AP (JK)			8.5	—	41.4	
Peak Emission Wavelength		λ_p	$I_F = 20 \text{ mA}$	—	644	—	nm
Spectral Line Half Width		$\Delta\lambda$	$I_F = 20 \text{ mA}$	—	18	—	nm
Dominant Wavelength		λ_d	$I_F = 20 \text{ mA}$	—	630	—	nm

(Note) : Lamps are classified into the following ranks according to their luminous intensity.
 Measurement tolerance for each limit is $\pm 15\%$.
 J : 10-20 mcd, K : 18-36 mcd, L : 32-64 mcd.

PRECAUTION

Please be careful of the followings

- Soldering temperature : 260°C max Soldering time : 3 s max
 (Soldering portion of lead : up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

